

# **A METHOD OF FORMING AN INTEGRATED CIRCUIT SUBSTRATE**

## **ABSTRACT OF THE DISCLOSURE**

5           A method of forming an integrated circuit substrate that may be adapted to  
be attached to one or more electronic components. The method includes applying a  
resist to a back side of a substrate which includes patterned conductive layers on a  
front side and a back side of the substrate. The method further includes removing  
part of the patterned conductive layer from the front side of the substrate to form  
10       pads and interconnects on the front side of the substrate and applying another resist  
to the front side of the substrate. The method also includes forming a pattern in  
each resist that exposes the pads on the front and back sides of the substrate and  
applying electrolytic nickel to the pads on the substrate.

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